



## Material Content Data Sheet



<b>Sales Product Name</b>		BTF3050EJ		<b>Issued</b>		9. January 2019		
<b>MA#</b>		MA002843814						
<b>Package</b>		PG-TDSO-8-31		<b>Weight*</b>		67.63 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.016	2.98	2.98	29807	29807
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		140	
	non noble metal	zinc	7440-66-6	0.038	0.06		562	
	non noble metal	iron	7439-89-6	0.760	1.12		11234	
wire	non noble metal	copper	7440-50-8	30.851	45.62	46.81	456161	468097
	non noble metal	copper	7440-50-8	0.380	0.56	0.56	5621	5621
	encapsulation	organic material	carbon black	1333-86-4	0.095	0.14		1400
plastics	plastics	epoxy resin	-	3.691	5.46		54582	
		inorganic material	silicondioxide	60676-86-0	27.765	41.05	46.65	410533
leadfinish	non noble metal	tin	7440-31-5	0.497	0.74	0.74	7352	7352
plating	noble metal	silver	7440-22-4	0.825	1.22	1.22	12195	12195
glue	plastics	epoxy resin	-	0.123	0.18		1822	
		noble metal	silver	7440-22-4	0.581	0.86	1.04	8591
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com